I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on <a href="https://www.example.com/www.ex

Kaun ing mars 4/26/03

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of \_\_\_\_: June 25, 2003

<u>Pogge et al.</u> : Group Art Unit:

Serial No. Not yet assigned : Examiner:

<u>Filed: Herewith</u>: IBM Corporation

This application is a Dept. 18G/Bldg. 300-482

division of: 2070 Route 52,

Serial No. 10/213,872 Hopewell Junction, NY 12533 Filed: August 6, 2002 :

Title: PROCESS FOR MAKING FINE

PITCH CONNECTIONS BETWEEN
DEVICES AND STRUCTURE MADE BY

THE PROCESS

## INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P. O. Box 1450 Arlington, VA 22313-1450

Sir:

As a means of complying with the duty of disclosure set forth in 37 CFR 1.56, Applicants are hereby filing an Information Disclosure Statement pursuant to 37 CFR 1.97 and 37 CFR 1.98. The references listed are those which were cited in

Applicants' parent patent application, Serial No. 09/669,531, issued as patent 6,444,560 on September 3, 2002, and Serial No. 10/213,872, CIP filed August 6, 2002.

A summary of all the references is made on Form PTO-1449, attached hereto. Pursuant to 37 CFR 1.98(d), copies of all the references are not being provided as they were previously cited and submitted in Applicants' parent Application noted above.

The Examiner is respectfully requested to consider each reference and initial a copy of Form PTO-1449 and return a copy of same to Applicants.

Respectfully submitted,
Pogge, et al.

Jak A. Anderson, Attorney Registration No. 38,371 Telephone No. (845) 894-3667

International Business Machines Corporation Zip 482 2070 Route 52 Hopewell Junction, NY 12533 Fax No. 845-892-6363

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Patent and Trademark Office-U.S. DEPARTMENT of COMMERCE (June 8, 1999)

INFORMATION DISCISSIFE CITATION (Use several sheets if necessary) Page 2 of 3  U.S. PATENT DOCUMENTS  Filing Date  Foreign PATENT DOCUMENTS  OTHER DOCUMENTS (Including Author, Title, Date, Fertinent Page, Etc.)  Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment,"  IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Kiao et al., "Tow Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, DATE CONSIDERED  DATE CONSIDERED
(Use several sheets if necessary) Page 2 of 3  U.S. PATENT DOCUMENTS    Filing Date   Group
U.S. PATENT DOCUMENTS    Page 2 of 3
U.S. PATENT DOCUMENTS  *Examiner Initial Document Number Date Name Class Subclass If Appropriate  5 3 5 3 4 9 8 10/11/94 Fillion et al.  5 3 7 3 6 2 7 12/20/94 Grebe  6 1 1 0 8 0 6 08/29/00 Pogge  FOREIGN PATENT DOCUMENTS  Document Number Date Country Class Subclass Translation Yes No  OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Page, Etc.)  Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment,"  IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).
#Examiner Initial Document Number Date Name Class Subclass If Appropriate    5   3   5   3   4   9   8   10/11/94   Fillion et al.
Initial Document Number Date Name Class Subclass If Appropriate  5 3 5 3 4 9 8 10/11/94 Fillion et al.  5 3 7 3 6 2 7 12/20/94 Grebe  6 1 1 0 8 6 6 08/29/00 Pogge  FOREIGN PATENT DOCUMENTS  FOREIGN PATENT DOCUMENTS  Translation  Translation  The Document Number Date Country Class Subclass Translation  The Notes of Patent Page, Etc.)  Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment,"  IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with  Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MIM Technology for High Volume,  Low Cost Electronics," Circuit World 21, 28 (1995).
FOREIGN PATENT DOCUMENTS  Class Subclass Translation  Document Number Date Country Class Subclass Wes No  OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Page, Etc.)  Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment,"  IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).
FOREIGN PATENT DOCUMENTS  FOREIGN PATENT DOCUMENTS  FOREIGN PATENT DOCUMENTS  FOREIGN PATENT DOCUMENTS  Translation Yes No  OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Page, Etc.)  Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment," IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).
FOREIGN PATENT DOCUMENTS  FOREIGN PATENT DOCUMENTS  Document Number Date Country Class Subclass Translation Yes No  OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Page, Etc.)  Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment," IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).
FOREIGN PATENT DOCUMENTS    Document Number   Date   Country   Class Subclass   Translation   Yes   No
FOREIGN PATENT DOCUMENTS    Document Number   Date   Country   Class Subclass   Translation   Yes   No
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Page, Etc.)  Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment," IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Page, Etc.)  Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment," IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Page, Etc.)  Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment," IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Page, Etc.)  Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment," IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Page, Etc.)  Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment," IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Page, Etc.)  Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment," IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).
Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment,"  IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).
Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment,"  IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).
Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment,"  IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).
Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment,"  IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).
Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment,"  IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).
Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment,"  IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with  Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume,  Low Cost Electronics," Circuit World 21, 28 (1995).
Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.  Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment,"  IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with  Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume,  Low Cost Electronics," Circuit World 21, 28 (1995).
Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment,"  IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with  Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume,  Low Cost Electronics," Circuit World 21, 28 (1995).
IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).
IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).  Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).
Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with  Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume,  Low Cost Electronics," Circuit World 21, 28 (1995).
Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).  R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume,  Low Cost Electronics," Circuit World 21, 28 (1995).
R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume,  Low Cost Electronics," Circuit World 21, 28 (1995).
R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume,  Low Cost Electronics," Circuit World 21, 28 (1995).
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Also form PTO-1449)  (June 8, 1999)

## SERIAL NO. ATTY DOCKET NO. FIS9-2000 0134US3 INFORMATION DISCLOSURE CITATION APPLICANT(S) (Use several sheets if necessary) H. BERNHARD POGGE Page 3 of 3 FILING DATE GROUP **U.S. PATENT DOCUMENTS** \*EXAMINER FILING DATE DOCUMENT NUMBER DATE NAME CLASS SUBCLASS INITIAL IF APPROPRIATE 6,025,638 02-15-00 POGGE ET AL. 6,066,513 05-23-00 POGGE ET AL. 12-07-99 5,998,868 POGGE ET AL. 07-11-00 6,087,199 POGGE ET AL. 11-02-93 5,258,236 Arjavalingam et al. 6,355,501 03-12-02 Fung et al. **FOREIGN PATENT DOCUMENTS** TRANSLATION DOCUMENT NUMBER DATE COUNTRY CLASS SUBCLASS OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.) "A Novel Chip-Stack Package" - Solid State Technology, April 2002, www.solid-state.com, pp. S19-S22, Eric Beyne, IMEC, Leuven, Belgium

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